



- Notes:**
1. All dimensions are in mm. Angles in degrees.
 2. Coplanarity applies to the exposed pad as well as the terminals.
 3. Refer JEDEC MO-229
 4. Thermal pad soldering area (mesh stencil design is recommended)

		DATE: 08/08/12
DESCRIPTION: 8-contact, Thin Dual-in-Line Flat Package (TDFN)		
PACKAGE CODE: ZA8		
DOCUMENT CONTROL #: PD-2068	REVISION: C	